

1752-2 1.1

Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

ICP Web Site for information on IPC-1752 Standard http://www.ipc.org/IPC-175x

Declaration Class* Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Form Type* Distribute Infomation

Supplier Information							
Company Name *	Company Unique ID	Unique ID Authority	Response Date*				
Fairchild Semiconductor	00-489-5751	Dun & Bradstreet	Sat, Feb 22, 2014 01:53 AM				
Contact Name * Title - Contact		Phone - Contact *	Email - Contact *				
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com				
Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *				
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com				

Requester Item Number	Mfr Ite	m Number	Mfr Item Name		Effective Date	Version	P	Manufacturing Site	Weight*	UOM	Unit Type
74AC138SCX	74AC138SCX 74AC138SCX		SOIC-16N	SOIC-16N			INTERNAL PENANG		PENANG 0.147797		Each
Manufacturing Process Information											
Terminal Finish	Base Alloy	J-STD-02	J-STD-020 MSL Rating		Peak Process Body Temperature		Max Time at Peak Temperature		No Reflow cycles		
Matte Tin (Sn)	CU Alloy		1		260	0 C 30 s		30 seconds		3	

* Required Field

RoHS Material	Composition Declaration	Declaration Type * Custom						
RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium							
restriction of the	Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the cou ise of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this docun irchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.							
ensure our production independently vertices	The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.							
Safety Data Sheet miniscule quantit	the content disclosed herewith is approximate and is based on various methods including, engineering calculations, is, analytical measurements. Fairchild may update this document without notification. This statement may not include of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed contain alternate substances of similar composition.	le information regarding the						
RoHS Declaration	* 1 - Item(s) does not contain RoHS restricted substances per the definition above Sup	plier Acceptance * Accepted						
II . F	ne declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exer ponse in the RoHS Declaration above and choose all applicable exemptions.	nptions, then select the						
Exemption None	List Version EL-2011/534/EU							
Declaration Sign	ature							

David Loncosto

Supplier Signature

DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name SOIC-16N

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	4.350	Supplier		Silicon	4.350	7440-21-3	29432
Die Attach	Other Organic Materials	0.440	Supplier		Acrylic Resin	0.095	54208-63-8	640
			Supplier		Silver	0.345	7440-22-4	2337
Encapsulation	Thermoplastics	93.900	В	Antimony/Antimony Compounds	Antimony Trioxide	1.878	1309-64-4	12707
			В	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	0.939	6386-73-8	6353
			Supplier		Carbon Black	0.704	1333-86-4	4765
			Supplier		Epoxy Resin	27.231	29690-82-2	184246
			Supplier		Silica, vitreous	63.148	60676-86-0	427260
Lead Frame	Copper & its alloys	46.400	Supplier		Copper	45.003	7440-50-8	304494
			Supplier		Iron	1.114	7439-89-6	7535
			Supplier		Phosphorus	0.019	7723-14-0	126
			Supplier		Silver	0.204	7440-22-4	1381
			Supplier		Zinc	0.060	7440-66-6	408
Plating	Other Nonferrous metals & alloys	2.310	Supplier		Tin	2.310	7440-31-5	15630
Wire Bond	Precious metals	0.397	Supplier		Gold	0.397	7440-57-5	2686